

Features

Functions for high-mix production



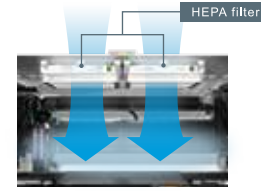
- Production can be continued because programs are created at an external computer.
- Production with high-accuracy and high-quality placements can be achieved by automatically performing calibration when nozzles and pots are exchanged.

Wafer map display



By automatically reading the wafer ID, the correct data can always be acquired. Data can be switched by automatically reading wafer IDs.

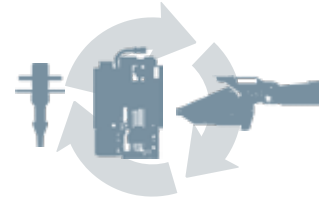
Inside the machine is kept clean



By installing a HEPA filter* with a particle collection efficiency of 99.97% or more in the machine the clean level in the machine is improved.

*: Option

Maintenance guidance



Heads, feeders, and nozzles have individual IDs, so reliable maintenance can be performed based on management and guidance from the system. Stable production can be performed with equipment in good condition all the time.



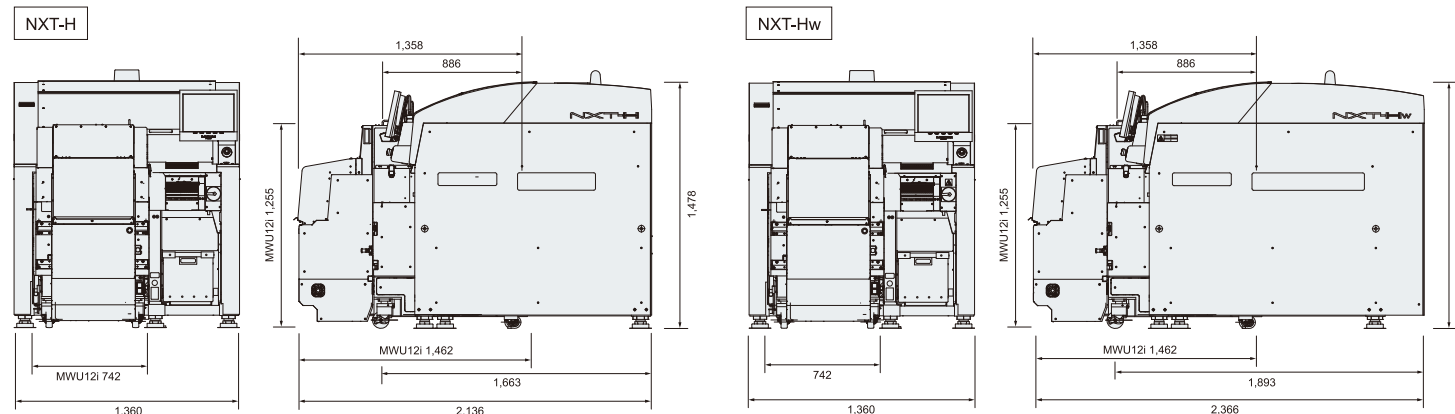
NXT-H

Fuji Ultra Accurate Placement Platform

Specifications		type FC	type SD	type LD
Heads		G04FQ	H24S / H24G	H08MQ
Placement accuracy ^{*1}		±0.008 mm	±0.020 mm	±0.015 mm
Die size ^{*2}		0.5 x 0.5 to 15 x 15 mm	0.5 x 0.5 to 5.0 x 5.0 mm	0.5 x 0.5 to 24 x 24 mm
Die thickness		0.08 to 6.5 mm	0.08 to 3 mm	0.08 to 6.5 mm
Minimum bump size		0.050 mm	-	-
Bump pitch		0.100 mm	-	-
Die	Throughput ^{*1}	Face-up	4,500 cph	13,400 cph
		Face-down	6,100 cph	-
			4,000 cph ^{*3}	-
Wafer size		4 to 12 inch		
Wafer magazine		25 or 13 slots		
Placement accuracy ^{*1}		±0.008 mm	±0.020 mm	±0.015 mm
Part sizes		0402 (01005") to 15 x 15 mm	0.2 x 0.2 to 5.0 x 5.0 mm	0603 (0201") to 24 x 24 mm
SMD	Throughput ^{*1}	NXT-H	5,200 cph	26,300 cph
		NXT-Hw		11,500 cph
Panel sizes (L x W)		NXT-H	48 x 48 to 610 x 380 mm	
		NXT-Hw	48 x 48 to 610 x 610 mm	
Power		3-phase AC200 to 230 V ±10% (50/60 Hz)		
Air		0.5 MPa (ANR)		
Air consumption		20 L/min (ANR) ^{*4}		
Weight		NXT-H + MWU12i	1,930 kg ^{*5}	1,910 kg

^{*1} Under optimum Fuji conditions.
^{*2} Please consult us if it is necessary to support 0.5 x 0.5 mm or less or thickness of 0.1 mm or less.
^{*3} Includes the flux dipping process.
^{*4} Add +90 L/min when using an MWU12i.
^{*5} When the configuration is NXT-H + MWU12i-FC.

Dimensions (mm)



Place SMDs and flip chips with one machine



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NXT-H

This machine is based on the surface mount technology for placing SMD parts at high speed and incorporates semi-conductor technology for placing die parts with high accuracy. The NXT-H allows you to go from a batch process using dedicated machines to an innovative inline production process.

Supports panels up to 610 x 610 mm

Wide range high-accuracy die placements
(Face down)

type FC

Fan-out PLP
DCB

Wide range high-speed die placements
(Face up)

type SD

For complex modules
such as
communication and
sensor modules

Multi chip SiP

Die placement (face down)
+ SMD placement

Flip chips
Flux transfer

type FC

Flip Chip
type FC



G04FQ head
4 nozzles

$\pm 0.008\text{mm}$

Small Die
type SD



H24S / H24G head
24 nozzles

13,400cph



Large Die
type LD



H08MQ head
8 nozzles

8,700cph

For small power modules
and sensor modules

Multi chip module
Power module

Die placement (face up)
+ SMD placement

type SD

Handles dies up to 24 x 24 mm

IGBT
Power module

Die placement (face up) + SMD placement

type LD

Can load dies and SMDs with different supply methods

Supports wafers from 4 to 12 inches. These different sizes can be loaded in the same magazine by using adapters.

Furthermore, up to 16 feeders for tape reels from 4 to 16 mm in width can be set on the fixed feeder table.



Modular concept that supports a many varieties of production types



- Inherits concepts from the NXT-series: our best-selling SMT mounter.

- Flexibly support different production types for flip chips, small dies, and large dies just by changing head types.

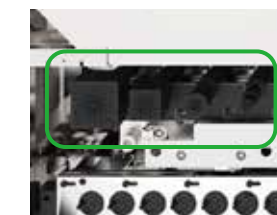


Supports flip chips and face-up supply

This machine can change between flip chip and face-up supply production methods as well as supply up to 25 different wafers.



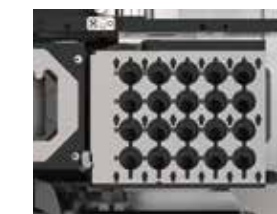
Automatic pusher pot exchange



This machine is equipped with a pusher pot changer and flip chip nozzle changer, so pusher pots and flip chip nozzles can be automatically exchanged during production.



Automatic nozzle exchange



There is a nozzle changer for automatically changing nozzles to match the parts being used.

